



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21A225KPFNNNG

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 2.2 µF, 10V, ±10%, X5R, 0805

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>A</u> <u>225</u> <u>K</u> <u>P</u> <u>F</u> <u>N</u> <u>N</u> <u>N</u> <u>G</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0805 (inch	code)	L: 2.0) ± 0.1	mm	W:	1.25 ± 0.1	mm
	Dialogatuia	VED		•	l	ala atua da		Ni	
3	Dielectric	X5R		(8)	inner e	electrode		INI	
4	Capacitance	2.2 μF			Termir	nation	(Cu	
(5)	Capacitance	±10 %			Plating	9	;	Sn 100%	(Pb Free)
	tolerance			9	Produc	ct	I	Normal	
6	Rated Voltage	10 V		10	Specia	ıl	I	Reserved for	future use
7	Thickness	1.25 ± 0.1	mm	11)	Packag	ging	I	Embossed T	ype, 7"reel(3,000ea)

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition				
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms				
Tan δ (DF)	0.05 max.					
Insulation	More than 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance						
Appearance	No abnormal exterior appearance	Visual inspection				
Withstanding	No dielectric breakdown or	250% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	X5R					
Characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120 ℃ for 10~30sec.)				
Decistance to	Constitute shares within 17.50/	O-1-1				
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	Tan δ, IR : initial spec.					

	Performance	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.075 max	40±2℃, 90~95%RH, 500+12/-0 hour				
	IR : More than 25MΩ· <i>μ</i> F					
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.075 max	Max. operating temperature				
	IR : More than 50MΩ· <i>μ</i> F					
		1000+48/-0 hour				
Temperature	Capacitance change: within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycles test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.